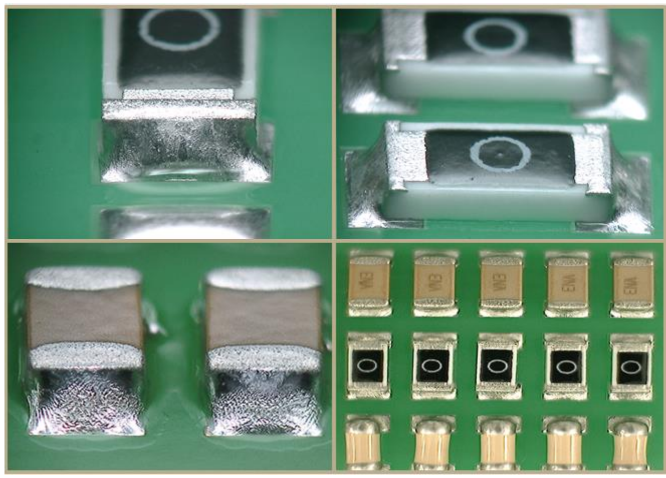
TECHNICAL DATA SHEET

NC258 (NO CLEAN) SOLDER PASTE

FEATURES

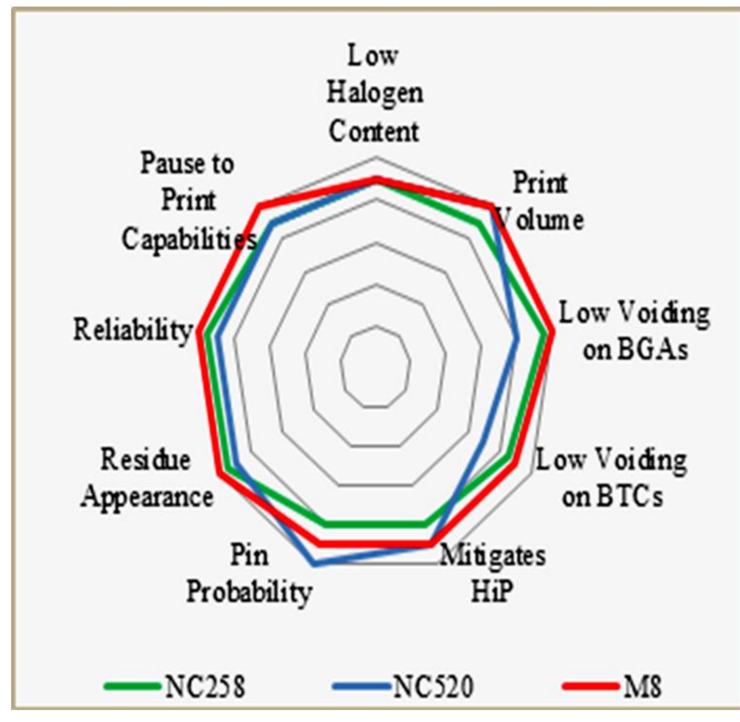
- Long Pause-to-Print Capabilities
- Excellent Wetting, Even Leadless Devices
- Reduces Voiding
- Low Post Process Residues
- RoHS Compliant
- Passes Bono Testing



DESCRIPTION

NC258 has been developed to offer long pause-to-print capabilities while enhancing fine print definitions. NC258 reduces voiding. The superior wetting ability of NC258 results in bright, smooth and shiny solder joints. It also offers very low post process residues, which remain crystal clear even at the elevated temperatures required for today's lead-free alloys.

CHARACTERISTICS



HANDLING & STORAGE

Parameter	Time	Temperature
Refrigerated Shelf Life	1 year	0°C - 12°C (32°F - 54°F)
Unrefrigerated Shelf Life	3 months	13°C - 22°C (55°F - 72°F)

Do not add used paste to unused paste. Store used paste separately; keep unused paste tightly sealed with internal plug or end cap in place. See AIM's paste handling guidelines for further information.

CLEANING

Pre-Reflow: AIM DJAW-10 effectively removes NC258 solder paste from stencils while in process. DJAW-10 can be hand applied or used in under stencil wipe equipment. DJAW-10 will not dry NC258 and will enhance transfer properties. Do not over-apply DJAW-10. Do not apply DJAW-10 to stencil topside. Isopropanol (IPA) is not recommended in process, but may be used as a final stencil rinse.

Post-Reflow Flux Residue: NC258 residues can remain on the assembly after reflow and do not require cleaning. Where cleaning is mandated, AIM has worked closely with industry partners to ensure that NC258 residues can be effectively removed with common defluxing agents. Contact AIM for cleaning compatibility information.

DISCLAIMER The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to http://www.aimsolder.com/terms-conditions to review AIM's terms and conditions.

WWW.AIMSOLDER.COM INFO@AIMSOLDER.COM
USA +1 401-463-5605 CANADA +1 514-494-2000 MEXICO +52 656-630-0032 ASIA +86 755-2993-6487 EUROPE +48 42-663-60-04

REFLOW PROFILE

Detailed profile information may be found at http://www.aimsolder.com/reflow-profile-supplements. Contact AIM for additional information.

PRINTING

Recommended Initial Printer Settings – Dependent on PCB and Pad Design	
Parameter	Recommended Initial Settings
Squeegee Pressure	0.9 – 1.5 lbs/inch of blade
Squeegee Speed	0.5 – 6 inches/second
Snap-off Distance	On Contact 0.00mm (0.00'')
PCB Separation Distance	0.75 – 2.0mm (.038 - .080'')
PCB Separation Speed	3.0 – 20.00 mm/second

TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ROL0	
IPC Flux Classification	J-STD-004B 3.3.1	ROL1	
Name	Test Method	Typical Results	Image
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	SAC305 NC258 / BLANK
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	Before / After

DISCLAIMER The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to http://www.aimsolder.com/terms-conditions to review AIM's terms and conditions.

PRELIMINARY

Name	Test Method	Typical Results	Image
Quantitative Halides, Chloride, Bromide	J-STD-004 3.2.4.3.1 IPC-TM-650 2.3.35 or 28	Br: 0.33% Cl: 0%	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	PASS See Aim Qualification Test Report #NC258052510	
Bono Testing		PASS Fc<8.0 Typical	
Oxygen Bomb Halogen Testing	EN14582:2007 SW 9056 SW 5050	Br <50.1 mg/Kg Cl <125 mg/Kg	
Electrochemical Migration	J-STD-004B 3.4.1.5 IPC-TM-650 2.6.14.1	PASS	
Flux Solids, Nonvolatile Determination	J-STD-004B 3.4.2.1 IPC-TM-650 2.3.34	99.89%	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	145 +/- 6mg KOH/g Flux	
Flux Specific Gravity Determination	J-STD-004B 3.4.2.3 ASTM D-1298	0.9223	
Viscosity	J-STD-004B 3.4.2.4 IPC-TM-650 2.4.34	600-900 depending on metal load and particle size	
Visual	J-STD-004B 3.4.2.5	PASS	

DISCLAIMER The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to http://www.aimsolder.com/terms-conditions to review AIM's terms and conditions.

PRELIMINARY

WWW.AIMSOLDER.COM INFO@AIMSOLDER.COM
USA +1 401-463-5605 CANADA +1 514-494-2000 MEXICO +52 656-630-0032 ASIA +86 755-2993-6487 EUROPE +48 42-663-60-04

Name	Test Method	Typical Results	Image
Slump	J-STD-005A 3.6 IPC-TM-650 2.4.35	PASS	
Solder Ball	J-STD-005A 3.7 IPC-TM-650 2.4.43	PASS	15Min 4Hr
Tack	J-STD-005A 3.8 IPC-TM-650 2.4.44	37.9g	SAC305 NC258 Tack (gf): 0.00, 20.00, 40.00, 60.00 Time (hour): T0 T1 T3 T4 T5 T6 T7 T8
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	

DISCLAIMER The information contained herein is based on data considered accurate and is offered at no charge. Product information is based upon the assumption of proper handling and operating conditions. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated. Please refer to http://www.aimsolder.com/terms-conditions to review AIM's terms and conditions.

PRELIMINARY

WWW.AIMSOLDER.COM INFO@AIMSOLDER.COM
USA +1 401-463-5605 CANADA +1 514-494-2000 MEXICO +52 656-630-0032 ASIA +86 755-2993-6487 EUROPE +48 42-663-60-04